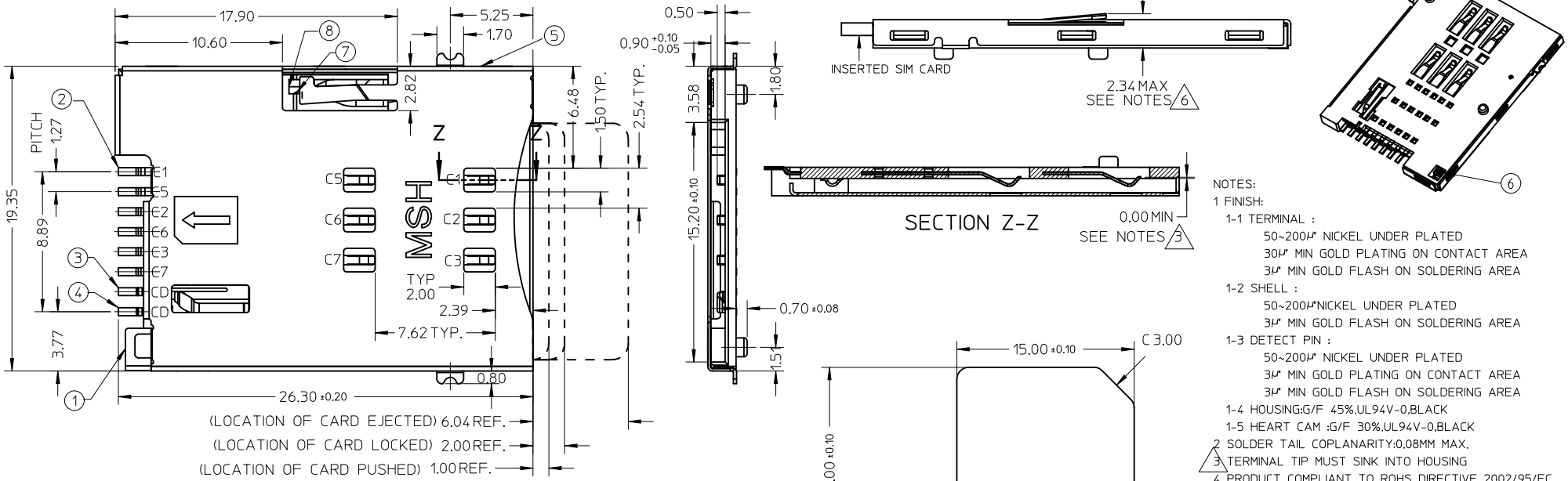

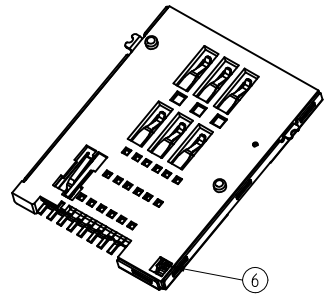

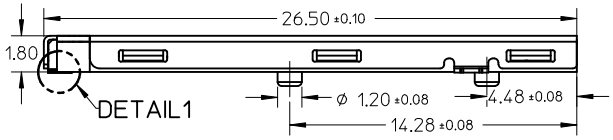

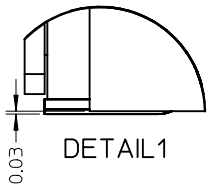

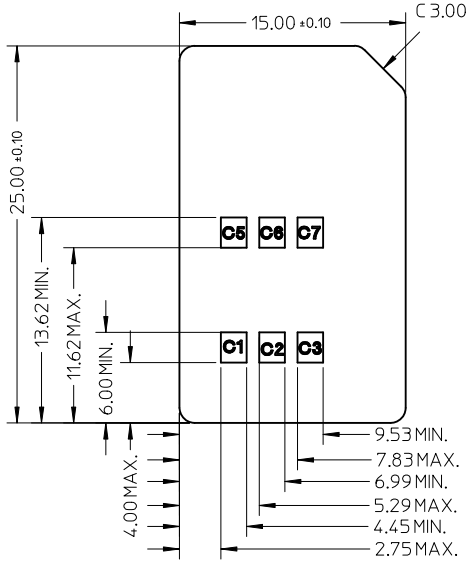

APPLICABLE CARD SIZE
THICKNESS:0.76+/-0.08

NOTES:
1 FINISH:
1-1 TERMINAL :
50~200μ" NICKEL UNDER PLATED
30μ" MIN GOLD PLATING ON CONTACT AREA
3μ" MIN GOLD FLASH ON SOLDERING AREA
1-2 SHELL :
50~200μ"NICKEL UNDER PLATED
3μ" MIN GOLD FLASH ON SOLDERING AREA
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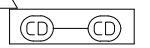
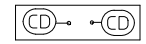
1-4 HOUSING:G/F 45%,UL94V-0,BLACK
1-5 HEART CAM :G/F 30%,UL94V-0,BLACK
2 SOLDER TAIL COPLANARITY:0.08MM MAX.
3 TERMINAL TIP MUST SINK INTO HOUSING
4 PRODUCT COMPLIANT TO ROHS DIRECTIVE 2002/95/EC AND ELV DIRECTIVE 2000/53/EC
5 DETECT SWITCH: INSERT CARD=ON (NORMAL=OPEN)
6 SPRING RISE UP DURING PUSH-PUSH PERIOD



CARD INSERTED



WITHOUT CARD

NO.	DESCRIPTION	Q'TY	MATERIAL
1	HOUSING	1	HIGH TEMPERATURE THERMOPLASTIC
2	TERMINAL	6	COPPER ALLOY
3	DETECT PIN LOWER	1	COPPER ALLOY
4	DETECT PIN UPPER	1	COPPER ALLOY
5	SHELLL	1	STAINLESS STEEL
6	COIL SPRING	1	PIANO WIRE
7	HEART CAM	1	NYLON
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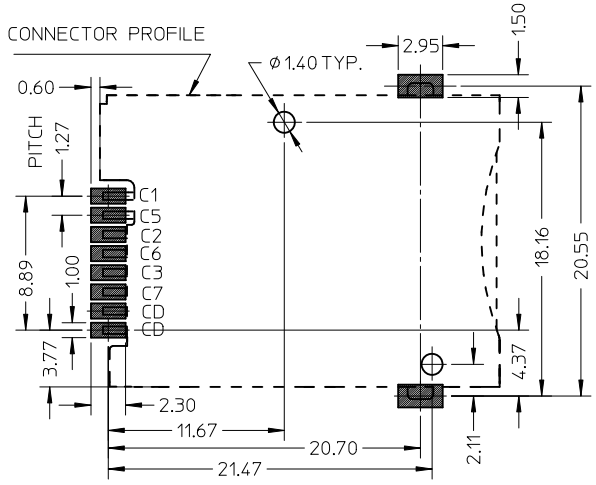


RECOMMENDED PCB LAYOUT
TOLERANCE +/-0.05MM

NEW DIM TOL CTRL
EC NO: S2011-0880
DRWN:KHLIM 2011/04/13
CH'KD:JTANG2 2011/04/25
APPR:SKTOH 2011/05/27
DESCRIPTION
REV
F1

QUALITY SYMBOLS
FA=0
FC=0
FP=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.15	± ---
1 PLACE	± ---	± ---
ANGULAR ±---°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

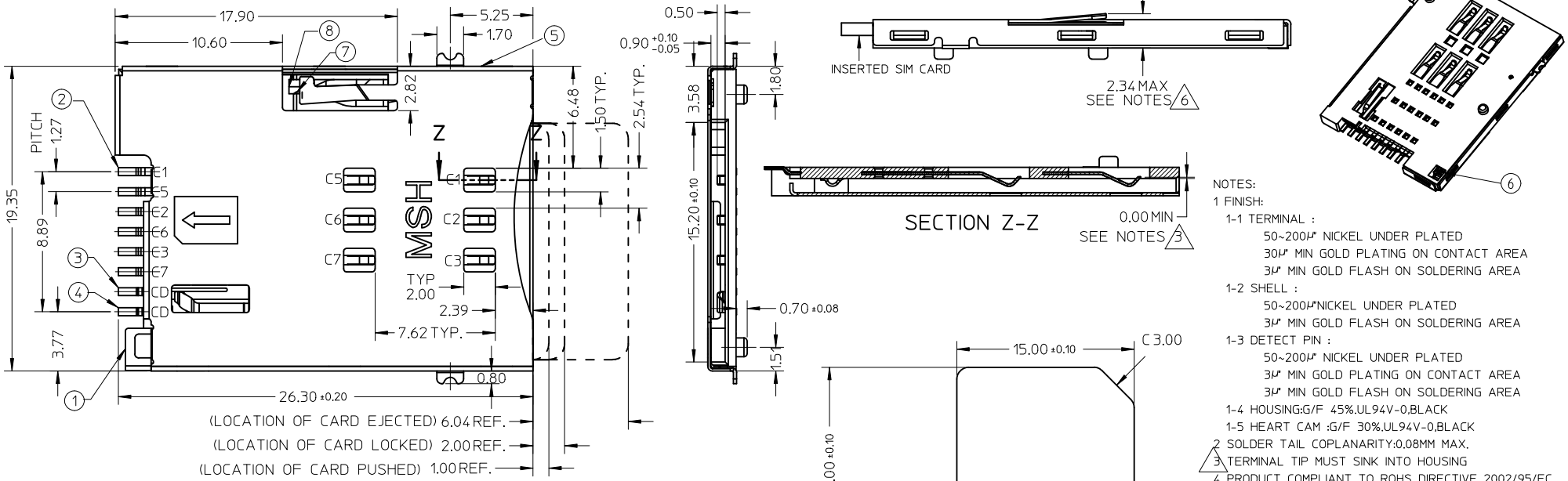
DRAWN BY: LHSHEN DATE: 2007/07/09
CHECKED BY: XUXIANG DATE: 2007/08/30
APPROVED BY: HWWANG DATE: 2007/08/30

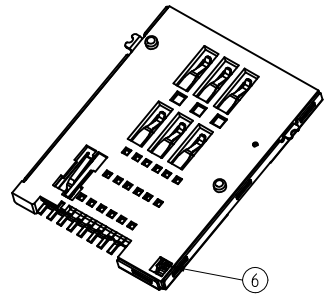
TITLE: PUSH PUSH 6 PINS SIM WITH DETECT PIN&POST SALES DRAWING

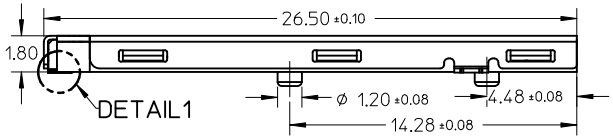
MOLEX INCORPORATED

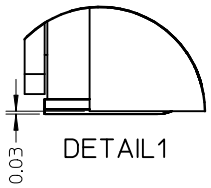
MATERIAL NO.: 475531001
DOCUMENT NO.: SD-47553-101
SHEET NO.: 1 OF 1
SIZE: A3

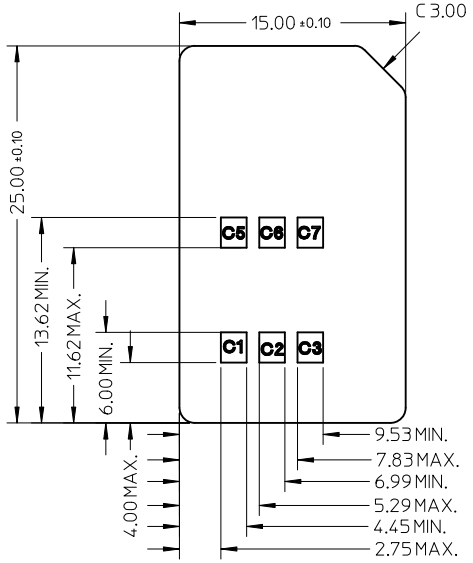
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION











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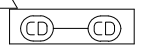

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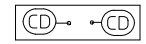

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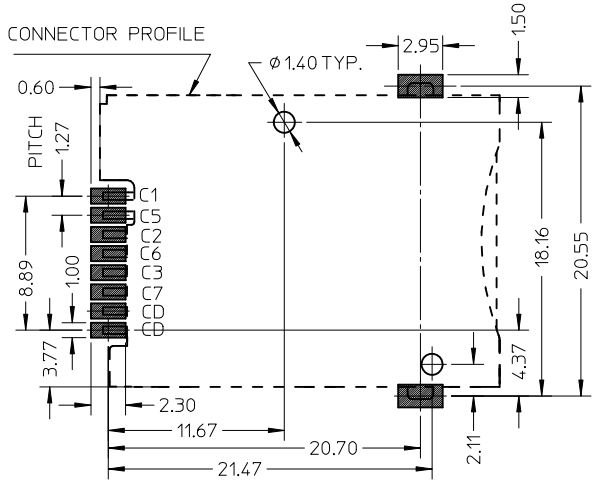

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